EPIGAP OSA

DATASHEET

EOLC-1720-21-1

Infrared InGaAs LED Chip

Features:

- Size: 1080 µm
- Thickness: 150 µm
- Au alloy pad: 130µm
- Bond-pad: n-up

Applications:

- Infrared sensing
- High power applications
- Industrial, scientific
- Biomedical, Sensing

RoHS COMPLIANT Pb-Free

Typical Electro-Optical Characteristics

Measurement conditions $T_{ambient}$ = 25 °C

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Emitting Color	Infrared					
Forward Voltage	V_f	I_f = 100 mA		0.75		V
		I_f = 1000 mA		1.1		V
Peak Wavelength	λ_D	I_f = 100 mA	1690	1720	1750	nm
FWHM	$\Delta\lambda$	I_f = 100 mA		129		nm
Radiant Power	P_o	I_f = 100 mA		14		mW
		I_f = 1000 mA		59		mW
Reverse Current	I_R	V_R = 5 V			5	µA
Rise Time	T_R	I_f = 100 mA		76		ns
Fall Time	T_F	I_f = 100 mA		142		ns

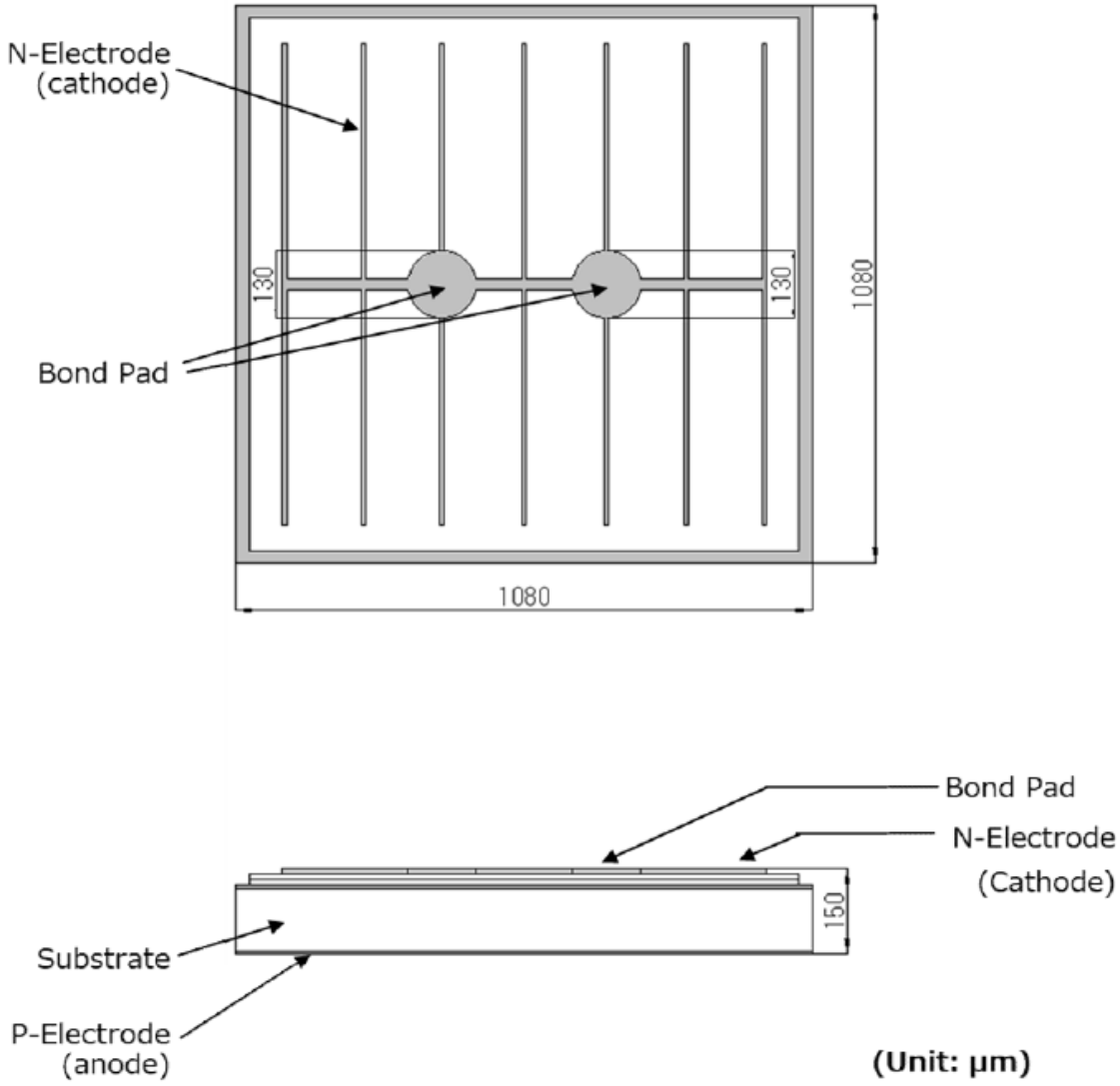
Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Forward Current (T = 25°C, infinite heatsink)	$I_{f, max}$		1000	mA
Reverse Voltage	V_R		5	V
Operating Temperature	T_{op}	-40	+85	°C

Mechanical Dimensions

Parameter	Value		Unit
Chip size	1080	±25	µm
Thickness	150	±10	µm
P-pad (bottom) / Au alloy	-	-	µm
N-pad (top) / Au alloy	130	±10	µm

Outline Drawing



Dice delivered on adhesive film.

Notice

The information describes the type of component and shall not consider as assured characteristics. Terms of delivery and rights to change reserved. The data sheet may change without prior notification; the only valid issue and current revision can be on our website. Due to technical requirements, components may contain dangerous substances.
It is the responsibility of the customer to evaluate and ensure that the use of the products in their specific applications complies with relevant safety standards and regulations. Customers must assess the exposure conditions within their systems and ensure that appropriate measures are taken to prevent exceeding the permissible exposure limits outlined in IEC 62471. EPIGAP OSA Photonics GmbH does not assume liability for any non-compliance arising from the integration or usage of LEDs in customer systems.
Parameters can vary in different applications. The customer must validate all operating parameters for each application. EPIGAP OSA Photonics GmbH does not have the responsibility for the reliability and the degradation behavior of products made with EPIGAP OSA Photonics GmbH diodes as they depend not only on the product itself but also on the operation, manufacturing or design of the final products. The customer is responsible for ensuring the long-term stability of the product according to their requirements. If components are used in toys or life support systems, EPIGAP OSA Photonics GmbH must expressly authorize the use of the components prior to incorporating them into the customer's systems!
Packaging: EPIGAP OSA Photonics GmbH uses recyclable packages.

EPIGAP OSA Photonics GmbH
www.epigap-osa.de

Köpenicker Str.325
12555 Berlin Germany
Tel. +49 (0)30 6576 3764
sales@epigap-osa.de